

C1210C333M2RACTU

Aliases (C1210C333M2RAC7800) SMD Comm X7R, Ceramic, 0.033 uF, 20%, 200 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 1210, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	40 mg
Shelf Life	78 Weeks
MSL	1

		Specifications	
	1210	Capacitance	0.033 uF
	3.2mm +/-0.2mm	Measurement Condition	1 kHz 1.0Vrms
	2.5mm +/-0.2mm	Tolerance	20%
	0.78mm +/-0.10mm	Voltage DC	200 VDC
	1.5mm MIN	Dielectric Withstanding Voltage	500 VDC
	0.5mm +/-0.25mm	Temperature Range	-55/+125°C
		Temp. Coefficient	X7R
tions		Capacitance Change with	15%, 1kHz 1.0Vrms
	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	

L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
т	0.78mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm
Packaging Specifications	

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Dimensions

Chip Size

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Dissipation Factor2.5% 1 kHz 1.0VrmsAging Rate3% Loss/Decade Hour: Referee Time is 1000 HoursInsulation Resistance30.303 GOhms)e	Reference to +25°C and 0 VDC Applied (TCC)	
Time is 1000 Hours		Dissipation Factor	2.5%1kHz1.0Vrms
Insulation Resistance 30.303 GOhms		Aging Rate	
		Insulation Resistance	30.303 GOhms

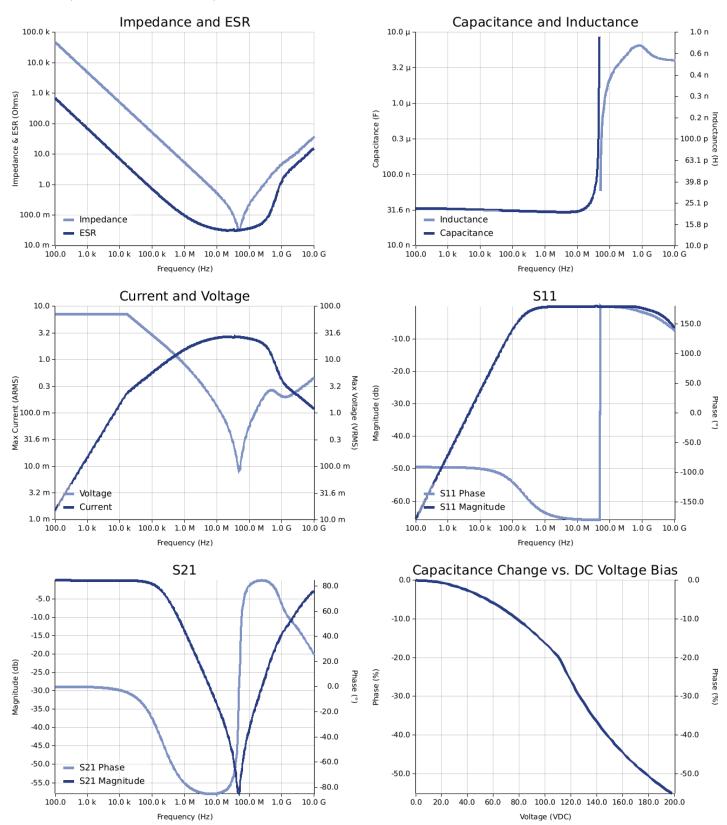
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Simulations

For the complete simulation environment please visit K-SIM.





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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.